Toshiba Intelligent Power Device Silicon Monolithic Power MOS Integrated Circuit

# **TPD1046F**

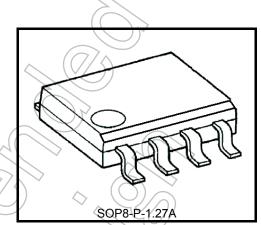
2-IN-1 Low-Side Power Switch for Motor, Solenoid and Lamp Drive

The TPD1046F is a 2-IN-1 low-side switch.

The IC has a vertical MOSFET output which can be directly driven from a CMOS or TTL logic circuit (e.g., an MPU). The IC is equipped with intelligent self-protection functions.

#### **Features**

- Two built-in power IC chips with a structure combining a control block and a vertical power MOSFET ( $L^2$ - $\pi$ -MOS) on each chip.
- Can directly drive a power load from a CMOS or TTL logic.
- Built-in protection circuits against overvoltage (active clamp), overtemperature (thermal shutdown), and overcurrent (current limiter).



Weight: 0.08 g (typ.)

- Low Drain-Source ON-resistance:  $RDS(ON) = 0.2 \Omega(max) (@V_{IN} = 5 \text{ V}, I_D \neq 1 \text{ A}, T_{ch} = 25^{\circ}\text{C})$
- Low Leakage Current:  $I_{DSS} = 10 \mu A (max) (@V_{IN} = 0 V, V_{DS} = 30 V, T_{ch} = 25^{\circ}C)$
- Low Input Current:  $I_{IN} = 600 \ \mu A (max) (@V_{IN} = 5 \ V, T_{ch} = -40 \sim 125 ^{\circ}C)$
- 8-pin SOP package with embossed-tape packing.

#### Pin Assignment (top view) Marking SOURCE1 8 DRAIN1 TPD1046 Part No. (or abbreviation code) DRAIN1 IN<sub>1</sub> Lot No. (weekly code) Note SOURCE2 DRAIN2 DRAIN2 (TOP VIEW)

Note: A line under a Lot No. identifies the indication of product Labels

Not underlined: [[Pb]]/INCLUDES > MCV

Underlined: [[G]]/RoHS COMPATIBLE or [[G]]/RoHS [[Pb]]

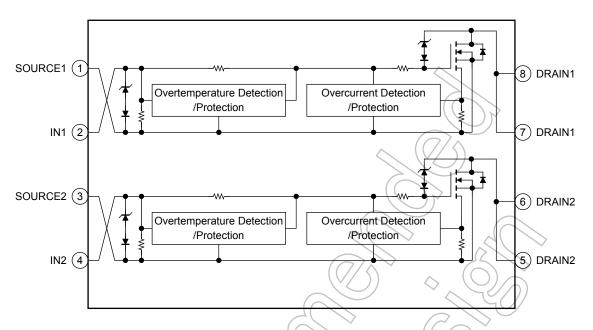
Please contact your TOSHIBA sales representative for details as to environmental matters such as the RoHS compatibility of Product.

The RoHS is Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

Due to its MOS structure, this product is sensitive to static electricity.

Start of commercial production 2005-05

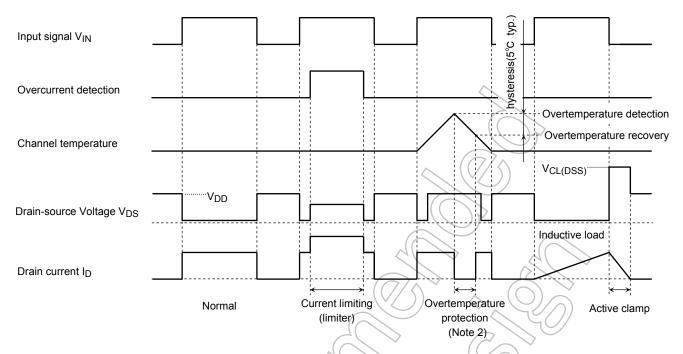
# **Block Diagram**



# **Pin Description**

Pin No.	Symbol	Pin Description
1	SOURCE1	Source pin 1
2	IN1	Input pin 1  This pin is connected to a pull-down resistor internally, so that even when input wiring is open-circuited, output can never be turned on inadvertently.
3	SOURCE2	Source pin 2
4	IN2	Input pin 2  This pin is connected to a pull-down resistor internally, so that even when input wiring is open-circuited, output can never be turned on inadvertently.
5, 6	DRAIN2	Drain pin 2  Drain current is limited (by current limiter) if it exceeds 3 A (min) in order to protect the IC.
7, 8	DRAIN1	Drain pin 1  Drain current is limited (by current limiter) if it exceeds 3 A (min) in order to protect the IC.

## **Timing Chart**



Note 2: The overtemperature detector circuits feature hysteresis. After overtemperature is detected, normal operation is restored only when the channel temperature falls by the hysteresis amount (5°C typ.) in relation to the overtemperature detection temperature.

#### **Truth Table**

V <sub>IN</sub>	V <sub>DS</sub>	Output State	Operating State
L	Н	OFF	Normal
Н	L	ON	Noma
L	Н	QFF QFF	Overcurrent
Н	Н	current limiting(limiter)	Overcurient
L	Н	OFF	Overtemperature
Н	Н	OFF	Overtemperature

## Absolute Maximum Ratings (Ta = 25°C)

Chara	cteristics	Symbol	ymbol Rating		
Drain-source voltage		V <sub>DS(DC)</sub>	40	V	
Drain current		I <sub>D</sub>	Internally Limited	Α	
Input voltage		$V_{IN}$	-0.3~7	V_\	
Power dissipation (Ta = 25°C) (Note 3-a)	1device operation (Note 4a)	P <sub>D(1)</sub>	0.95	w	
	2 devices operation per device (Note 4b)	P <sub>D(2)</sub>	0.54	W	
Power dissipation	1device operation (Note 4a)	P <sub>D(1)</sub>	0.38	W	
(Ta = 25°C) (Note 3-b)	2 devices operation per device (Note 4b)	P <sub>D(2)</sub>	0.20	_w	
Single pulse active clamp tolerance (Note 5)		E <sub>AS</sub>	97	mJ	
Active clamp current		I <sub>AR</sub>	3	Α	
Repetitive active clamp	tolerance (Note 3-a) (Note 6)	E <sub>AR</sub>	54	Çığ	
Operating temperature		Topr	<b>−40~125</b>	°C /	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature		T <sub>stg</sub>	_55~150		

#### **Thermal Characteristics**

Characteristics	Symbol	max	Unit		
Thermal resistance, channel to	1device operation (Note 4a)	R <sub>th</sub> (ch-a)(1)	132	°C/W	
ambient (Note 3-a)	2 devices operation per device (Note 4b)	R <sub>th</sub> (ch-a)(2)	231		
Thermal resistance, channel to	1device operation (Note 4a)	Rth (ch-a)(1)	330	°C/W	
ambient (Note 3-b)	2 devices operation per device (Note 4b)	R <sub>th</sub> (ch-a)(2)	625		

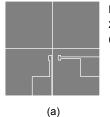
Note:

Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings and the operating ranges.

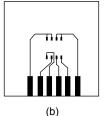
Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 3:

3-a: glass epoxy board (a)



FR-4 25.4 × 25.4 × 0.8 (unit: mm) 3-b : glass epoxy board (b)



FR-4 25.4 × 25.4 × 0.8 (unit: mm)

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#### Note 4:

- 1 device operation: power dissipation value or thermal resistance of one side device. a)
- b) 2 devices operation per device : power dissipation value or thermal resistance per device when power is impressed evenly.

Note 5: V<sub>DD</sub> = 25 V, T<sub>ch</sub> = 25°C(initial), L = 10.8 mH, I<sub>AR</sub> = 3 A, R<sub>G</sub> = 25  $\,\Omega$  Note 6: Repetitive rating : Pulse width limited by maximum channel temperature.



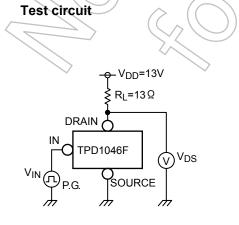
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### **Electrical Characteristics**

Characteristics		Symbol	Test Circuit	Test Condition		Min	Тур.	Max	Unit	
Drain-source clamp voltage		V (CL) DSS	-	T <sub>ch</sub> = 25°C	V <sub>IN</sub> = 0 V, I <sub>D</sub> = 1 mA	40	49	60	V	
				T <sub>ch</sub> = -40~125°C		40	ı	60		
Input threshold voltage		V <sub>th</sub>	1	T <sub>ch</sub> = 25°C	V <sub>DS</sub> = 13 V, I <sub>D</sub> = 10 mA	1.0	1.6	2.8	V	
				$T_{ch} = -40 \sim 125$ °C		0.9	,	3.0		
Protective circuit of voltage range	pperation input	V <sub>IN (opr)</sub>	-	$T_{ch} = -40 \sim 125^{\circ}C$	-	4	· -	7	>	
Drain cut-off current		lana	-	T <sub>ch</sub> = 25°C	V <sub>IN</sub> = 0 V, V <sub>DS</sub> = 12 V	<b>/</b> <del>}</del>	-	10	μΑ	
		I <sub>DSS</sub>		$T_{ch} = -40 \sim 125$ °C		<u> </u>	-	30		
		lus zas			V <sub>IN</sub> = 5 V,	> -	130	600		
		I <sub>IH</sub> (1)	_	T <sub>ch</sub> = -40~125°C	at normal operation	-		600		
High level input current		I <sub>IH (2)</sub>	-	T <sub>ch</sub> = -40~125°C	V <sub>IN</sub> = 5 V, when protective circuit is actuated	- <		2000	μΑ	
Drain-source on resistance		R <sub>DS</sub> (ON)	-	$T_{ch} = 25^{\circ}C$ $T_{ch} = -40 \sim 125^{\circ}C$	V <sub>IN</sub> = 5 V, I <sub>D</sub> = 1 A	7.7	0.14	0.2	Ω	
Load-short tolerance		V <sub>DS</sub>	-	T <sub>ch</sub> = -40~125°C	V <sub>IN</sub> = 4~6 V	20	-	-	V	
Overtemperature	temperature detection	T <sub>OT(1)</sub>	-		V <sub>IN</sub> = 5 V	150	160	1	°C	
detection	temperature recovery	T <sub>OT2()</sub>	4(	<u>"</u> //		125	155	-	°C	
Overcurrent detect	Over a company of a fact a figure		t detection		$T_{ch} = 25^{\circ}C$	V <sub>IN</sub> = 5 V	3.0	3.7	ı	Α
Overcurrent detection		loc		T <sub>ch</sub> = -40~125°C	2.0	-	-	Α .		
Switching time		toff		T <sub>ch</sub> = 25°C	V <sub>DD</sub> = 13 V, V <sub>IN</sub> = 0 V/5 V,	-	15	100	μs	
			)) <sub>1</sub>	$T_{ch} = -40 \sim 125^{\circ}C$		-	-	100		
			T <sub>ch</sub> = 25°C	$R_L = 13 \Omega$	-	30	100	μζ		
				$T_{ch} = -40 \sim 125$ °C		-	-	100		
Drain-source diode forward voltage		VDSF		T <sub>ch</sub> = 25°C	V <sub>IN</sub> = 0 V, I <sub>F</sub> = 1 A	-	-	1.7	V	

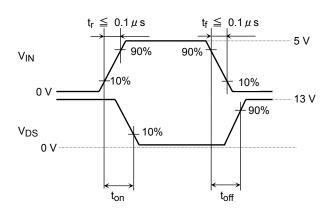
## Test Circuit 1

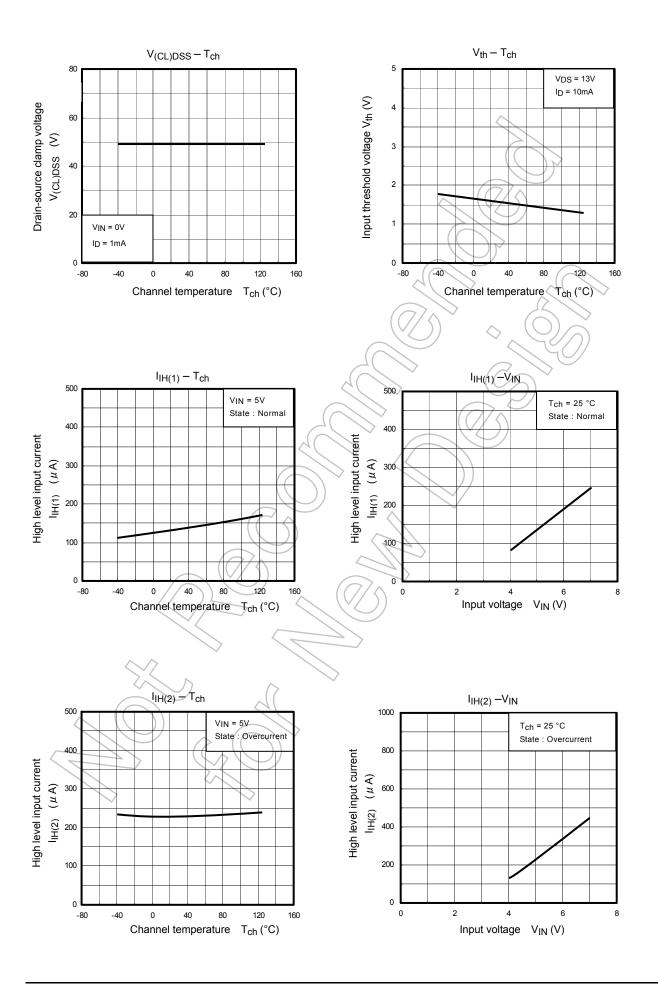
# Switching time measuring circuit

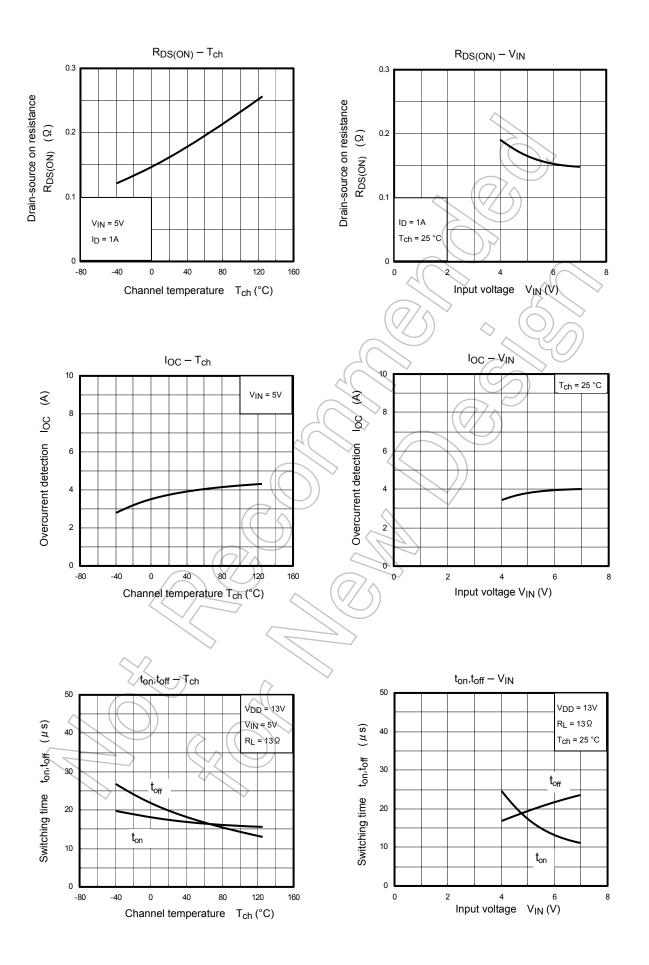


#### **Measured waveforms**

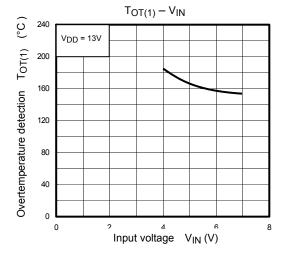
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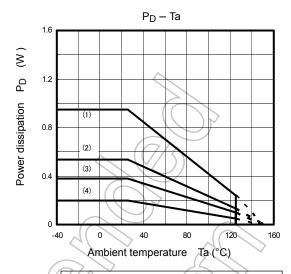






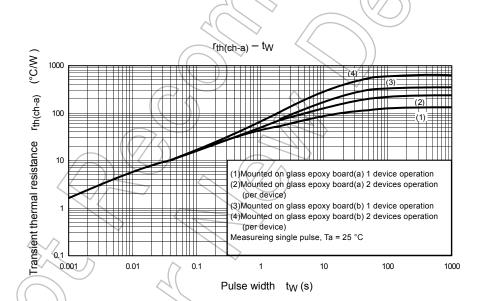
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(1)Mounted on glass epoxy board(a) 1 device operation (2)Mounted on glass epoxy board(a) 2 devices operation (per device)

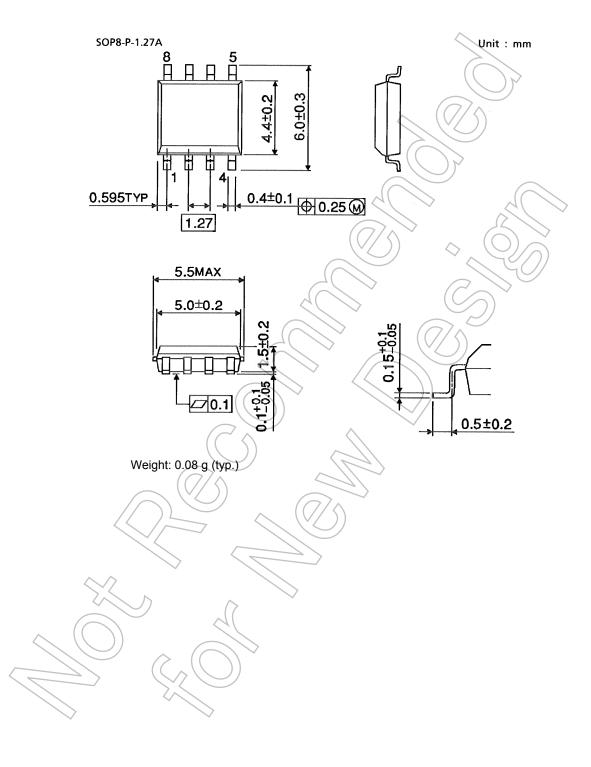
(3)Mounted on glass epoxy board(b) 1 device operation (4)Mounted on glass epoxy board(b) 2 devices operation (per device)



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# **Package Dimensions**



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